# The RF Line NPN Silicon RF Power Transistor

... designed primarily for applications as a high–power linear amplifier from 2.0 to 30 MHz, in single sideband mobile, marine and base station equipment.

Specified 28 Volt, 30 MHz Characteristics —
 Output Power = 80 W (PEP)
 Minimum Gain = 15 dB
 Efficiency = 40%

Intermodulation Distortion = -32 dB (Max)

#### **MATCHING PROCEDURE**

In the push–pull circuit configuration it is preferred that the transistors are used as matched pairs to obtain optimum performance.

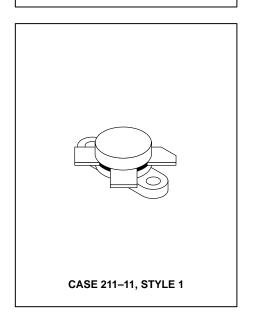
The matching procedure used by Motorola consists of measuring hpe at the data sheet conditions and color coding the device to predetermined hpe ranges within the normal hpe limits. A color dot is added to the marking on top of the cap. Any two devices with the same color dot can be paired together to form a matched set of units.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCEO	35	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	65	Vdc
Emitter-Base Voltage	VEBO	4.0	Vdc
Collector Current — Continuous	IC	10	Adc
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	PD	250 1.4	Watts W/°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C

# **MRF464**

80 W (PEP), 30 MHz RF POWER TRANSISTOR NPN SILICON



#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{ heta JC}$	0.7	°C/W
Stud Torque (1)	_	8.5	In. Lb.

#### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Breakdown Voltage (IC = 100 mAdc, IB = 0)	V(BR)CEO	35	_	Vdc
Collector–Emitter Breakdown Voltage (IC = 100 mAdc, VBE = 0)	V(BR)CES	65	_	Vdc
Emitter–Base Breakdown Voltage (IE = 1.0 mAdc, IC = 0)	V(BR)EBO	4.0	_	Vdc
Collector Cutoff Current (V <sub>CE</sub> = 28 Vdc, V <sub>BE</sub> = 0, T <sub>C</sub> = +55°C)	ICES	_	10	mAdc
ON CHARACTERISTICS	•			
DC Current Gain (I <sub>C</sub> = 0.5 Adc, V <sub>CE</sub> = 5.0 Vdc)	hFE	10	_	_

NOTE:
1. Case 145A–10 — For Repeated Assembly Use 11 In. Lb.

(continued)

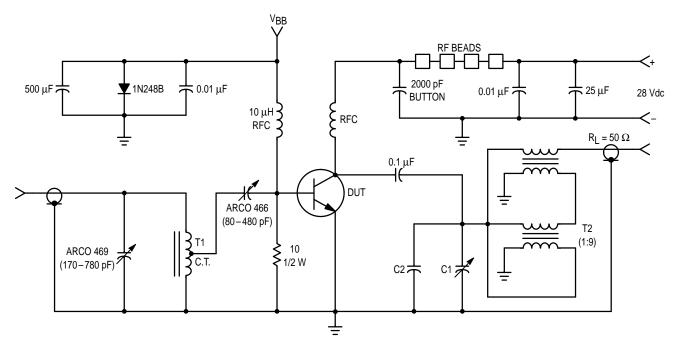


## **ELECTRICAL CHARACTERISTICS** — **continued** ( $T_C = 25$ °C unless otherwise noted.)

Characteristic	Symbol	Min	Max	Unit
DYNAMIC CHARACTERISTICS	•			
Output Capacitance (V <sub>CB</sub> = 28 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>ob</sub>	_	200	pF
FUNCTIONAL TESTS				
Common–Emitter Amplifier Power Gain (Figure 1) ( $P_{Out} = 80 \text{ W (PEP)}$ , $I_C = 3.6 \text{ Adc (Max)}$ , $V_{CC} = 28 \text{ Vdc}$ , $f_1 = 30 \text{ MHz}$ , $f_2 = 30.001 \text{ MHz}$ )	GPE	15	_	dB
Intermodulation Distortion Ratio (Figure 1) (2) ( $P_{out}$ = 80 W (PEP), $I_C$ = 3.6 Adc (Max), $V_{CC}$ = 28 Vdc, $f_1$ = 30 MHz, $f_2$ = 30.001 MHz)	IMD	_	-32	dB
Collector Efficiency ( $P_{out}$ = 80 W (PEP), $I_C$ = 3.6 Adc (Max), $V_{CC}$ = 28 Vdc, $f_1$ = 30 MHz, $f_2$ = 30.001 MHz)	η	40	_	%

#### NOTE:

2. To Mil-Std-1311 Version A, Test Method 2204B, Two Tone, Reference each Tone.



RFC — 20 Turns @12 AWG Enameled Wire Close Wound in 2 Layers, 1/4" I.D.
 T1 — 20 Turns #24 AWG Wire Wound on Micro–Metals T37–7 Toroid Core Center Tapped.

T2 — 1:9 XFMR; 6 Turns of 2 Twisted Pairs of #28 AWG Enameled Wire.
(8 Crests Per Inch) Bifilar Wound on Each of 2 Separate Balun Cores.
(Stackpole #57–1503, No. 14 Material) Interconnected as shown
RF Beads — Ferroxcube #56–590–65/3B

VBB adjusted for I<sub>CQ</sub> — 40 mAdc (I<sub>CQ</sub> = Quiescent Collector Current)

 $\mathrm{C1} - 170 - 180~\mathrm{pF}$  ARCO 469 or Equivalent  $\mathrm{C2} - 330~\mathrm{pF}$ 

Figure 1. 30 MHz Test Circuit

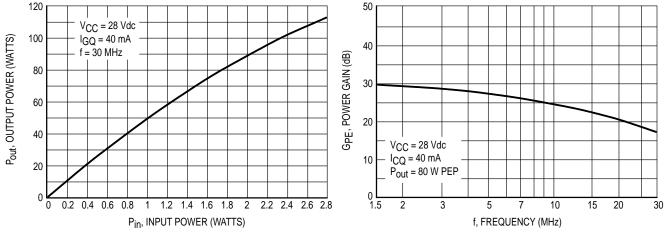


Figure 2. Output Power versus Input Power

Figure 3. Power Gain versus Frequency

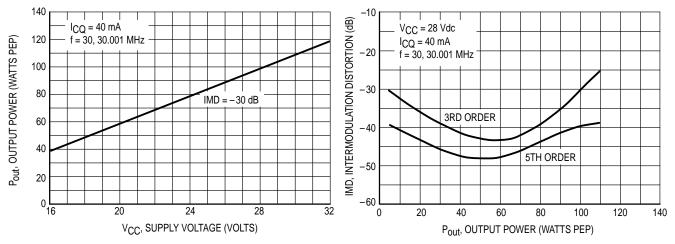


Figure 4. Output Power versus Supply Voltage

Figure 5. Intermodulation Distortion versus **Output Power** 

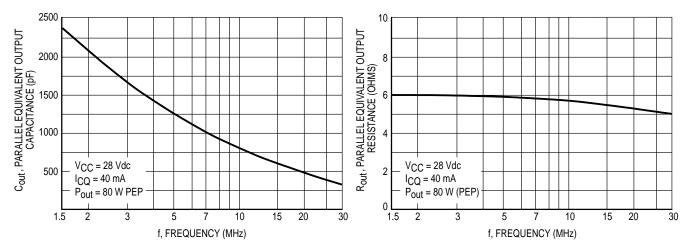


Figure 6. Output Capacitance versus Frequency

Figure 7. Output Resistance versus Frequency

MOTOROLA RF DEVICE DATA **MRF464** 

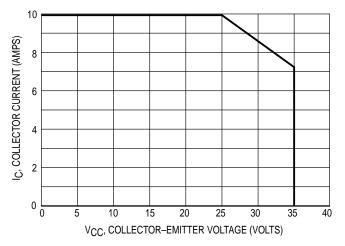


Figure 8. DC Safe Operating Area

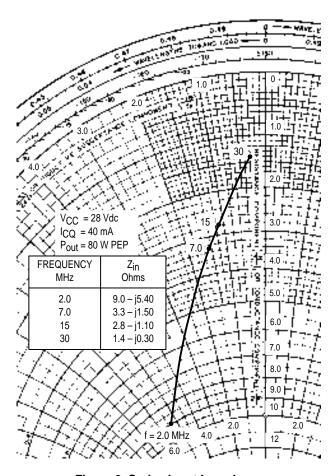
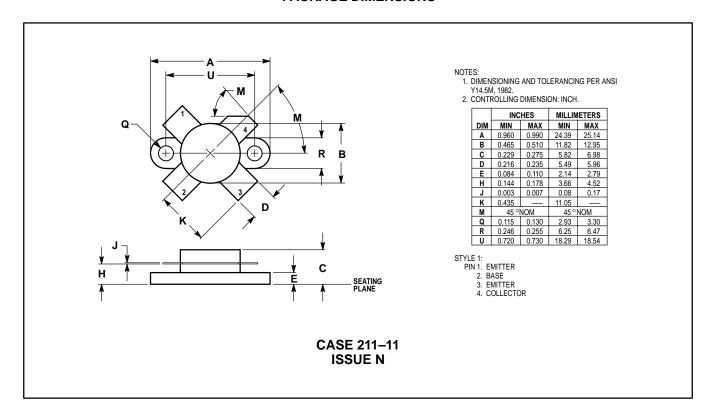


Figure 9. Series Input Impedance

### **PACKAGE DIMENSIONS**



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